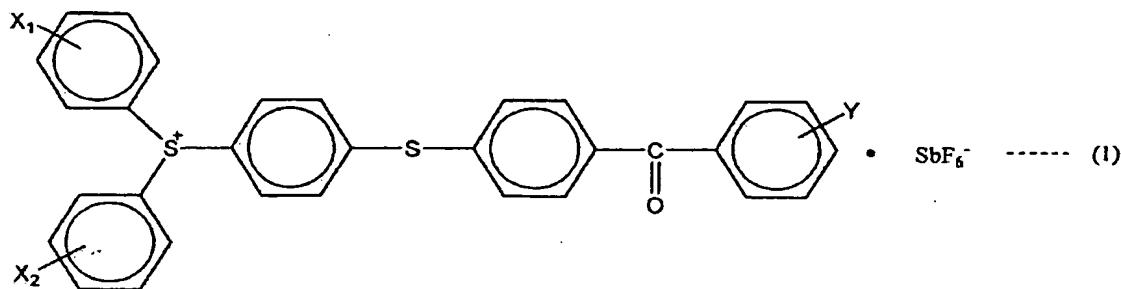


ABSTRACT

A photosensitive resin composition comprises a multi-functional epoxy resin and a cation polymerization initiator represented by general formula (1) shown below:



(in the formura (1), X_1 and X_2 indicate a hydrogen atom, a halogen atom, a hydrocarbon group which may contain an oxygen atom or a halogen atom, or an alkoxy group to which a substituent may bond, and they may be identical to or different from one another. Y indicates a hydrogen atom, a halogen atom, a hydrocarbon group which may contain an oxygen atom or a halogen atom, or an alkoxy group to which a substituent may bond). The photosensitive resin composition is used as a pattern formation composition.